# 3.3V Differential LVPECL to LVTTL Translator

The MC100EPT21 is a Differential LVPECL to LVTTL translator. Because LVPECL (Positive ECL) levels are used only +3.3 V and ground are required. The small outline 8-lead SOIC package makes the EPT21 ideal for applications which require the translation of a clock or data signal.

The  $V_{BB}$  output allows this EPT21 to be cap coupled in either single–ended or differential input mode. When single–ended cap coupled,  $V_{BB}$  output is tied to the  $\overline{D}$  input and D is driven for a non–inverting buffer, or  $V_{BB}$  output is tied to the D input and  $\overline{D}$  is driven for an inverting buffer. When cap coupled differentially,  $V_{BB}$  output is connected through a resistor to each input pin. If used, the  $V_{BB}$  pin should be bypassed to  $V_{CC}$  via a 0.01  $\mu F$  capacitor. For additional information see AND8020. For a single–ended direct connection use an external voltage reference source such as a resistor divider. Do not use  $V_{BB}$  for a single–ended direct connection or port to another device.

- 1.4 ns Typical Propagation Delay
- Maximum Frequency > 275 MHz Typical
- 24 mA TTL outputs
- Operating Range:  $V_{CC} = 3.0 \text{ V}$  to 3.6 V with GND = 0 V
- Open Input Default State
- Q Output Will Default LOW with Inputs Open or at GND
- The 100 Series Contains Temperature Compensation
- V<sub>BB</sub> Output
- New Differential Input Common Mode Range



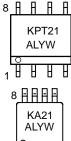
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SO-8 D SUFFIX CASE 751



8 **(1)** 

TSSOP-8 DT SUFFIX CASE 948R

A = Assembly Location

L = Wafer Lot

Y = Year

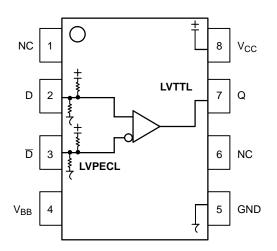
W = Work Week

\*For additional information, see Application Note AND8002/D

# **ORDERING INFORMATION**

Device	Package	Shipping†	
MC100EPT21D	SO-8	98 Units/Rail	
MC100EPT21DR2	C100EPT21DR2 SO-8		
MC100EPT21DT	TSSOP-8	100 Units/Rail	
MC100EPT21DTR2	TSSOP-8	2500 Tape & Reel	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



PIN DESCRIPTION

PIN	FUNCTION
Q	LVTTL Output
D**, \( \overline{D}**	Differential LVPECL Input Pair
V <sub>CC</sub>	Positive Supply
V <sub>BB</sub>	Output Reference Voltage
GND	Ground
NC	No Connect

<sup>\*\*</sup> Pins will default to V<sub>CC</sub>/2 when left open.

Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

# **ATTRIBUTES**

Characteri	Value	
Internal Input Pulldown Resistor	50 kΩ	
Internal Input Pullup Resistor	50 kΩ	
ESD Protection	Human Body Model Machine Model Charged Device Model	> 1.5 kV > 100 V > 2 kV
Moisture Sensitivity, Indefinite Time	Level 1	
Flammability Rating	UL 94 V-0 @ 0.125 in	
Transistor Count	81 Devices	
Meets or exceeds JEDEC Spec EIA	VJESD78 IC Latchup Test	

<sup>1.</sup> For additional information, see Application Note AND8003/D.

# MAXIMUM RATINGS (Note 2)

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V <sub>CC</sub>	PECL Power Supply	GND = 0 V		3.8	V
V <sub>IN</sub>	PECL Input Voltage	GND = 0 V	$V_{I} \leq V_{CC}$	0 to 3.8	V
I <sub>BB</sub>	V <sub>BB</sub> Sink/Source			± 0.5	mA
TA	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
$\theta_{\sf JA}$	Thermal Resistance (Junction–to–Ambient)	0 LFPM 500 LFPM	8 SOIC 8 SOIC	190 130	°C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	std bd	8 SOIC	41 to 44	°C/W
$\theta_{JA}$	Thermal Resistance (Junction–to–Ambient)	0 LFPM 500 LFPM	8 TSSOP 8 TSSOP	185 140	°C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	std bd	8 TSSOP	41 to 44	°C/W
T <sub>sol</sub>	Wave Solder	< 2 to 3 sec @ 248°C		265	°C

<sup>2.</sup> Maximum Ratings are those values beyond which device damage may occur.

# PECL INPUT DC CHARACTERISTICS $V_{CC} = 3.3 \text{ V, GND} = 0.0 \text{ V (Note 3)}$

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	2075		2420	2075		2420	2075		2420	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended)	1355		1675	1355		1675	1355		1675	mV
V <sub>BB</sub>	Output Voltage Reference	1775	1875	1975	1775	1875	1975	1775	1875	1975	V
V <sub>IHCMR</sub>	Input HIGH Voltage Common Mode Range (Differential) (Note 4)	2.0		3.3	2.0		3.3	2.0		3.3	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μΑ
I <sub>IL</sub>	Input LOW Current [			0.5	-150		0.5	-150		0.5	μΑ

NOTE: Devices are designed to meet the DC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

- Input parameters vary 1:1 with V<sub>CC</sub>.
   V<sub>IHCMR</sub> min varies 1:1 with GND, V<sub>IHCMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>IHCMR</sub> range is referenced to the most positive side of the differential input signal.

# TTL OUTPUT DC CHARACTERISTICS $V_{CC} = 3.3 \text{ V}$ , GND = 0.0 V, $T_A = -40 ^{\circ}\text{C}$ to $85 ^{\circ}\text{C}$

Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V <sub>OH</sub>	Output HIGH Voltage	$I_{OH} = -3.0 \text{ mA}$	2.4			V
V <sub>OL</sub>	Output LOW Voltage	I <sub>OL</sub> = 24 mA			0.5	V
I <sub>CCH</sub>	Power Supply Current	Outputs set to HIGH	5	12	20	mA
I <sub>CCL</sub>	Power Supply Current	Outputs set to LOW	8	18	26	mA
Ios	Output Short Circuit Current		-130		-80	mA

# AC CHARACTERISTICS $V_{CC} = 3.0 \text{ V}$ to 3.6 V, GND = 0.0 V (Note 5)

			–40°C		25°C		85°C					
Symbol	Characteristic		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f <sub>max</sub>	Maximum Frequency (See Figure 2. F <sub>max</sub> /JITTER)		275	350		275	350		275	350		MHz
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay to Output Differential		1200 1200	1450 1400	1800 1800	1200 1200	1450 1400	1800 1800	1300 1200	1450 1400	1900 1900	ps
t <sub>SKPP</sub>	Part-to-Part Skew (Note 6)				500			500			500	ps
t <sub>JITTER</sub>	Random Clock Jitter (RMS) (See Figure 2 F <sub>max</sub> /JITTER)			0.2	< 1		0.2	< 1		0.2	< 1	ps
V <sub>PP</sub>	Input Voltage Swing (Differential)		150	800	1200	150	800	1200	150	800	1200	mV
t <sub>r</sub>	Output Rise/Fall Times (0.8V – 2.0V)	$Q, \overline{Q}$	330	500	900	330	500	900	330	500	900	ps

- 5. Measured with a 750 mV 50% duty-cycle clock source.  $R_L$  = 500  $\Omega$  to GND and  $C_L$  = 20 pF to GND. Refer to Figure 3. 6. Skews are measured between outputs under identical transitions.

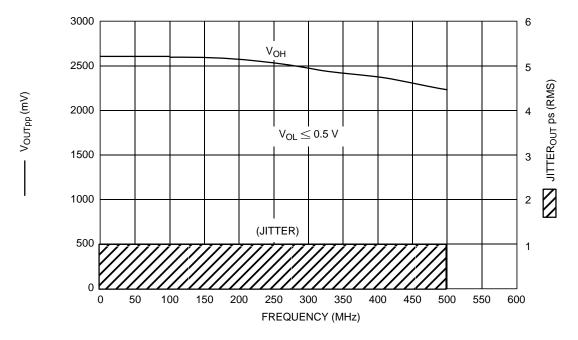


Figure 2. F<sub>max</sub>/Jitter

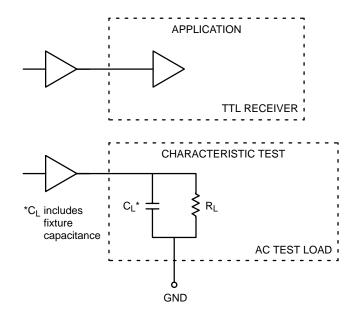


Figure 3. TTL Output Loading Used For Device Evaluation

# **Resource Reference of Application Notes**

AN1404 – ECLinPS Circuit Performance at Non–Standard V<sub>IH</sub> Levels

AN1405 – ECL Clock Distribution Techniques

AN1406 – Designing with PECL (ECL at +5.0 V)

AN1504 – Metastability and the ECLinPS Family

AN1568 – Interfacing Between LVDS and ECL

AN1650 - Using Wire-OR Ties in ECLinPS Designs

AND8002 – Marking and Date Codes

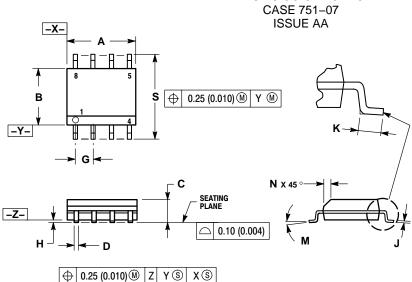
AND8009 - ECLinPS Plus Spice I/O Model Kit

AND8020 - Termination of ECL Logic Devices

For an updated list of Application Notes, please see our website at http://onsemi.com.

# **PACKAGE DIMENSIONS**

# SO-8 **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751-07

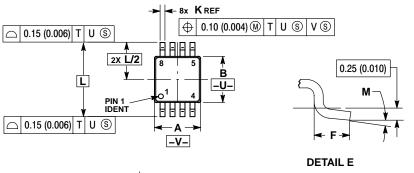


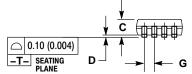
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
  6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDAARD IS 751-07

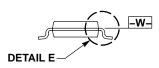
	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
K	0.40	1.27	0.016	0.050	
M	0 °	8 °	0 °	8 °	
N	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

#### **PACKAGE DIMENSIONS**

#### TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**







#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. TERMINAL NI IMBERS ARE SHOWN FOR

- PER SIDE.
  5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
  6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE W–.

	MILLIN	IETERS	HES		
DIM	MIN	MIN MAX MIN			
Α	2.90	3.10	0.114	0.122	
В	2.90	3.10	0.114	0.122	
С	0.80	1.10	0.031	0.043	
D	0.05	0.15	0.002	0.006	
F	0.40	0.70	0.016	0.028	
G	0.65	BSC	0.026	BSC	
K	0.25	0.40	0.010	0.016	
L	4.90	BSC	0.193	BSC	
M	0°	6 °	0°	6°	

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